

## PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Chia-Yu Hung</td> <td>07/31/2012</td> </tr> <tr> <td>Tsung-Li Yeh</td> <td>07/31/2012</td> </tr> <tr> <td>Yi-Chang Tu</td> <td>07/31/2012</td> </tr> </tbody> </table>		Name	Execution Date	Chia-Yu Hung	07/31/2012	Tsung-Li Yeh	07/31/2012	Yi-Chang Tu	07/31/2012
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RECEIVING PARTY DATA									
<table border="1"> <tr> <td>Name:</td> <td>Realtek Semiconductor Corp.</td> </tr> <tr> <td>Street Address:</td> <td>2 Innovation Rd. II, Science Park</td> </tr> <tr> <td>City:</td> <td>HsinChu</td> </tr> <tr> <td>State/Country:</td> <td>TAIWAN</td> </tr> </table>		Name:	Realtek Semiconductor Corp.	Street Address:	2 Innovation Rd. II, Science Park	City:	HsinChu	State/Country:	TAIWAN
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PROPERTY NUMBERS Total: 1									
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Application Number:	13563752								
CORRESPONDENCE DATA									
<p>Fax Number: 7039974517</p> <p>Phone: 3027291562</p> <p>Email: Patent.admin.uspto.cr@naipo.com</p> <p><i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i></p> <p>Correspondent Name: WINSTON HSU</p> <p>Address Line 1: P.O.BOX 506</p> <p>Address Line 4: Merrifield, VIRGINIA 22116</p>									
ATTORNEY DOCKET NUMBER:	REAP0640USA								
NAME OF SUBMITTER:	SHELLEY KUO								
<p>Total Attachments: 2</p> <p>source=1430667#page1.tif</p> <p>source=1430667#page2.tif</p>									

CH \$40.00 13563752

**ASSIGNMENT OF INVENTION**

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

**ASSIGNOR(S) (Inventors):**

Name: Chia-Yu Hung Nationality: TW

Name: Tsung-Li Yeh Nationality: TW

Name: Yi-Chang Tu Nationality: TW

Hereby sells, assigns and transfers to

**ASSIGNEE(S):**

Name: Realtek Semiconductor Corp.

Address: 2 Innovation Rd. II, Science Park, HsinChu 30076, Taiwan, R.O.C.

and the successors and assignees of the ASSIGNEE the entire right, title, and interest in and to any and all improvements which are disclosed in the invention entitled:

**"SIGNAL PROCESSING APPARATUS"**

Which is found in :

- (a) + U.S. patent application executed on even date
- (b) \_\_\_\_\_ U.S. patent application executed on \_\_\_\_\_
- (c) \_\_\_\_\_ U.S. application serial no. \_\_\_\_\_
- (d) \_\_\_\_\_ patent no. \_\_\_\_\_ issued \_\_\_\_\_
- (e) \_\_\_\_\_ International application no. \_\_\_\_\_

PATENT

and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.

IN WITNESS WHEREOF, We have hereunto set hand and seal this JUL 31 2012 (Date of signing). (請發明人務必簽署上列日期。)

(Type name of inventor)

**Signature of INVENTOR**

Chia-Yu Hung

Chia-Yu Hung

Tsung-Li Yeh

Tsung-Li Yeh

Yi-Chang Tu

Yi-Chang Tu